

What is claimed is:

1. Electronic component for connecting a plurality of electrodes, comprising:

5 an insulative base having a plurality of electrodes and spaces therebetween,

an anisotropic conductive adhesive agent applied on to the electrodes,

10 an insulative adhesive agent, having the same curing condition as a curing condition of the anisotropic conductive adhesive agent, applied on to the spaces,

wherein each of the anisotropic conductive adhesive agent and the insulative adhesive agent is temporarily cured.

2. Electronic component for connecting a plurality of electrodes, 15 comprising:

an insulative chip cover with a radiating portion and having a housing portion on a lower surface thereof,

20 a flip chip piece, composed of a base having a plurality of electrodes of a semiconductor element arranged on a back surface, accommodated in the housing portion,

an anisotropic conductive adhesive agent applied or screen-printed on the electrodes of the base of the chip piece,

an bonding surface located on a circumference of the chip piece and on a lower surface of the insulative chip cover,

25 an insulative adhesive agent, having the same curing condition as a curing condition of the anisotropic conductive adhesive agent, applied or screen-printed on to the bonding surface,

30 wherein each of the anisotropic conductive adhesive agent and the insulative adhesive agent is press-heated for a predetermined time to temporarily be cured.

3. Electronic component for connecting a plurality of electrodes according to claim 2, wherein the radiating portion is composed of an opening portion provided on at least one end surface of the chip cover and

communicated with exterior of the chip cover.

4. Electronic component for connecting a plurality of electrodes according to claim 2, wherein the insulative adhesive agent has a similar 5 temperature property as that of the anisotropic conductive adhesive agent having a property of being active to a heating temperature and changed from a temporarily cured state to a cured state.

5. A method of mounting electronic component for connection of a 10 plurality of electrode, comprising the steps of:

15 accommodating a flip chip piece into a chip cover, wherein the flip chip piece has a semiconductor element with a plurality of electrodes arranged in a planar fashion, and a housing portion is provided on a lower surface of the chip cover made of an insulative material and having a radiating portion,

20 applying or screen-printing an anisotropic conductive adhesive agent to a plurality of electrodes provided on a base of the chip piece, and applying or screen-printing an insulative adhesive agent having the same curing condition as that of the anisotropic conductive adhesive agent to an bonding surface of the chip cover,

heat-pressing the anisotropic conductive adhesive agent and the insulative adhesive agent to temporarily curing the anisotropic conductive adhesive agent and the insulative adhesive agent to thereby produce a predetermined electronic component,

25 providing the electronic component in position on a circuit board having substrate electrodes arranged to be aligned with the electrode of the chip piece to provide a predetermined positioning of the electrodes and the substrate electrodes, and

30 mounting a crimping tool on the chip cover and lowering the crimping tool as the above-mentioned two types of the adhesive agents are being hot melted to press the chip cover on to the circuit board for a predetermined time to electrically connect the aforementioned two types of electrodes with each other.